Abstract

Provided are a temperature control method for an inspection system and an inspection system, the inspection system inspecting a substrate while performing temperature control by suppressing overshoot of a junction temperature of an electronic device. The temperature control method is for an inspection system comprising a chuck that holds a substrate having an electronic device to be inspected, and a tester that applies inspection power to the electronic device to inspect the electronic device. The method comprises: a step for obtaining a model of a first transfer function of a temperature rise of the electronic device from heat generation due to application of the inspection power to the electronic device; a step for obtaining a model of a second transfer function of the temperature of the chuck when a set temperature of the chuck is changed; a step for acquiring an inspection timing of the electronic device from the tester; and a step for starting temperature control of the chuck on the basis of the first transfer function and the second transfer function prior to the start of inspection of the electronic device.